L Number	Hits	Search Text	DB	Time stamp
-	334	29/829.ccls.	USPAT;	2002/12/10 15:46
	202	20/942 colo	US-PGPUB	00004040454540
-	302	29/842.ccls.	USPAT; US-PGPUB	2002/12/10 15:46
•	763	29/874.ccls.	USPAT;	2002/12/10 15:46
			US-PGPUB	2002/12/10 10:40
-	387	29/884.ccls.	USPAT;	2002/12/11 14:06
			US-PGPUB	
-	69	29/884.ccls. and @py<2000 and (taper\$2 cone conical)	USPAT;	2002/12/11 14:04
	85	29/874.ccls. and @py<2000 and (taper\$2 cone conical)	US-PGPUB	2002/12/14 44:27
-	0.5	25/6/4.ccis. and @py\2000 and (taper\$2 cone conicar)	USPAT; US-PGPUB	2002/12/11 14:37
_	76	(29/874.ccls. and @py<2000 and (taper\$2 cone conical)) not	USPAT;	2002/12/11 14:07
		29/884.ccls.	US-PGPUB	
•	687	29/874.ccls. not ((29/874.ccls. and @py<2000 and (taper\$2	USPAT;	2002/12/11 14:37
		cone conical)) not 29/884.ccls.)	US-PGPUB	
•	609	(29/874.ccls. not ((29/874.ccls. and @py<2000 and (taper\$2	USPAT;	2002/12/11 14:37
_	131	cone conical)) not 29/884.ccls.)) and @py<2000 ((29/874.ccls. not ((29/874.ccls. and @py<2000 and (taper\$2	US-PGPUB USPAT;	2002/12/11 14:38
_	131	cone conical)) not 29/884.ccls.)) and @py<2000 and (taper\$2	US-PGPUB	2002/12/11 14.30
		method.ti.	001000	
-	52	(((29/874.ccls. not ((29/874.ccls. and @py<2000 and (taper\$2	USPAT;	2002/12/11 15:12
		cone conical)) not 29/884.ccls.)) and @py<2000) and	US-PGPUB	
		method.ti.) and (printed adj circuit adj board pc adj board		
	4077	substrate wafer laminat\$2)	LICOAT	000040444544
-	1077	216/41, 44.ccls. and @py<2000	USPAT; US-PGPUB	2002/12/11 15:11
_	808	(216/41, 44.ccls. and @py<2000) and (printed adj circuit adj	USPAT;	2002/12/12 15:50
	000	board pc adj board substrate wafer laminat\$2)	US-PGPUB	2002/12/12 10:00
-	79	((216/41, 44 ccls. and @py<2000) and (printed adj circuit adj	USPAT;	2002/12/11 15:14
		board pc adj board substrate wafer laminat\$2)) and corros\$3	US-PGPUB	
•	71	((216/41, 44.ccls. and @py<2000) and (printed adj circuit adj	USPAT;	2002/12/12 13:30
		board pc adj board substrate wafer laminat\$2)) and method.ti. and (corros\$3 salt salin\$3)	US-PGPUB	
_	1	6171164.pn.	USPAT;	2002/12/11 15:41
:	·		US-PGPUB	2002/12/11 10:41
-	1	5391259.pn.	USPAT;	2002/12/12 13:34
			US-PGPUB	
-	1	5302238.pn.	USPAT;	2002/12/12 14:02
	205	257/775 colo	US-PGPUB	0000/40/40 44:00
-	385	257/775.ccls.	USPAT; US-PGPUB	2002/12/12 14:03
_	237	257/775.ccls. and @py<2000	USPAT;	2002/12/12 14:24
			US-PGPUB	2002/12/12 11:21
-	43	(257/775.ccls. and @py<2000) and method.ti.	USPAT;	2002/12/12 14:24
			US-PGPUB	
-	264	438/754.ccls.	USPAT;	2002/12/12 14:49
	. 63	439/754 colo. and @ny<3000 and mathed ti	US-PGPUB	2002/42/42 44:50
-	62	438/754.ccls. and @py<2000 and method.ti.	USPAT; US-PGPUB	2002/12/12 14:50
_	96	438/673.ccls.	USPAT;	2002/12/12 15:44
		100/01 0.00/0.	US-PGPUB	2002/12/12 10:44
-	31	438/673.ccls. and @py<2000 and method.ti.	USPAT;	2002/12/12 15:47
			US-PGPUB	
-	567	438/669.ccls.	USPAT;	2002/12/12 15:44
	204	439/660 calc. and @ny.<2000 and mathed ti	US-PGPUB	2002/42/42 45:40
-	201	438/669.ccls. and @py<2000 and method.ti.	USPAT; US-PGPUB	2002/12/12 15:49
_	185	(438/669.ccls. and @py<2000 and method.ti.) and (printed adj	USPAT;	2002/12/12 16:10
	103	circuit adj board pc adj board substrate wafer laminat\$2) not	US-PGPUB	2002/12/12 10:10
		((257/775.ccls. and @py<2000) and method.ti.) not		
		(438/754.ccls. and @py<2000 and method.ti.) not		
		(438/673.ccls. and @py<2000 and method.ti.)		
-	789020	printed adj circuit adj board pc adj board substrate wafer	USPAT;	2002/12/12 16:26
1		laminat\$2) (plated plating) (rhodium palladium gold	US-PGPUB	·

-	909334	(printed adj circuit adj board pc adj board substrate wafer laminat\$2) (plated plating) (rhodium palladium gold) and (etch	USPAT;	2002/12/12 16:22
		remov\$2) anisotropic (taper\$3 cone conical)	US-PGPUB	
-	16041	(printed adj circuit adj board pc adj board substrate wafer) and ((plated plating) same (rhodium palladium gold))	USPAT; US-PGPUB	2002/12/12 16:26
-	772	((printed adj circuit adj board pc adj board substrate wafer) and ((plated plating) same (rhodium palladium gold))) and	USPAT;	2002/12/12 16:28
		(tetch remov\$2) and anisotropic and (taper\$3 cone conical point\$2 sharp)	US-PGPUB	
-	159	(((printed adj circuit adj board pc adj board substrate wafer) and ((plated plating) same (rhodium palladium gold))) and (etch remov\$2) and anisotropic and (taper\$3 cone conical	USPAT; US-PGPUB	2002/12/12 16:32
		point\$2 sharp)) and (contact bump\$2 electrode) and method.ti. and @py<2000		